



03-23-2005



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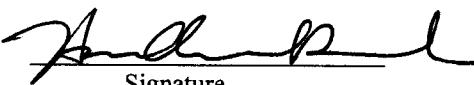
FORM PTO-1595
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J.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office
Docket No.: 6161.0500.US

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies): Keun-Soo LEE; Byoung-Keon PARK</p> <p>Additional names of conveying party(ies) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p> <p>3. Nature of Conveyance</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____</p> <p>Execution Date: March 11, 2005</p>	<p>2. Name and address of receiving party(ies): Name: Samsung SDI Co., Ltd.</p> <p>Internal Address:</p> <p>Street Address: 575, Shin-dong, Yeongtong-gu, City: Suwon-si, Gyeonggi-do State or Country: The Republic of KOREA</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p>
<p>4. Application number(s) or patent number(s):</p> <p style="text-align: center;">TITLE: THIN FILM TRANSISTOR AND METHOD OF FABRICATING THE SAME</p> <p>If this document is being filed together with a new application, the execution date of the application is</p> <p>A. Patent Application No(s). 11/019,456, filed December 23, 2004</p> <p>B. Patent No(s).</p> <p style="text-align: right;">Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Hae-Chan Park McGuireWoods LLP 1750 Tysons Boulevard, Suite 1800 McLean, Virginia 22102</p>	<p>6. Total number of applications and patents involved: <u>1</u></p> <p>7. Total fee (37 CFR 3.41): \$40.00</p> <p><input checked="" type="checkbox"/> Enclosed</p> <p><input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Total fee due <input checked="" type="checkbox"/> Any deficiencies in the enclosed fees</p> <p>8. Deposit account number: 23-1951</p>
<p>9. Statement and signature</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</p> <p><u>Hae-Chan Park, Reg. No. 50,114</u>  <u>March 18, 2005</u> Name of Person Signing Signature Date</p>	

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Docket No.: 6161.0500.US

ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

- an application for United States Letters Patent entitled **THIN FILM TRANSISTOR AND METHOD OF FABRICATING THE SAME** ("Application");
- upon which United States Letters Patent, Patent Number _____, has issued ("Patent");

Whereas, Assignor desires to convey all rights, title and interests in and to the same to Samsung SDI Co., Ltd. ("Assignee"), with offices located at 575, Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, The Republic of KOREA;

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the invention disclosed in said application and in and to any Letters Patent of the United States, any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or inventor's certificates and related rights heretofore or hereafter filed for the invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the U.S. or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

Assignor:

Signature: Keun Soo Lee

Print Name: Keun-Soo LEE

Address: 575, Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Rep. of Korea

Date: March 11, 2005

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Assignor:

Signature: Park Byoung Keon

Print Name: Byoung-Keon PARK

Address: 575, Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Rep. of Korea

Date: March 11, 2005